



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US 01

AF/1746  
13k  
BH  
7-21-01  
(NE)

*Do not enter*  
In re the application of: )  
Ramachandran et al. ) Group Art: 1746  
Serial No.: 09/204,706 )  
Examiner: A. Olsen  
Filing Date: December 3, 1998 )  
Title: REMOVAL OF POST-RIE POLYMER )  
ON Al/Cu METAL LINE )

JUL 19 2001  
RC 1700 MAIL ROOM

RECEIVED

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed Jun 27, 2001, which rejected the claims in the above-identified patent application, applicants respectfully request reconsideration, based upon the amendments hereinafter set forth

IN THE CLAIMS:

13. (Twice Amended) In a metal etch tool for removing post-RIE polymer rails formed on a Al/Cu metal line of a semiconductor structure, the improvement comprising an integrated metal etch tool comprising therein: [separate] strip chamber means [for

forming a water-only plasma process] to strip the photo-resist layer of a semiconductor composite structure with water only plasma subsequent [previously subjected] to a RIE